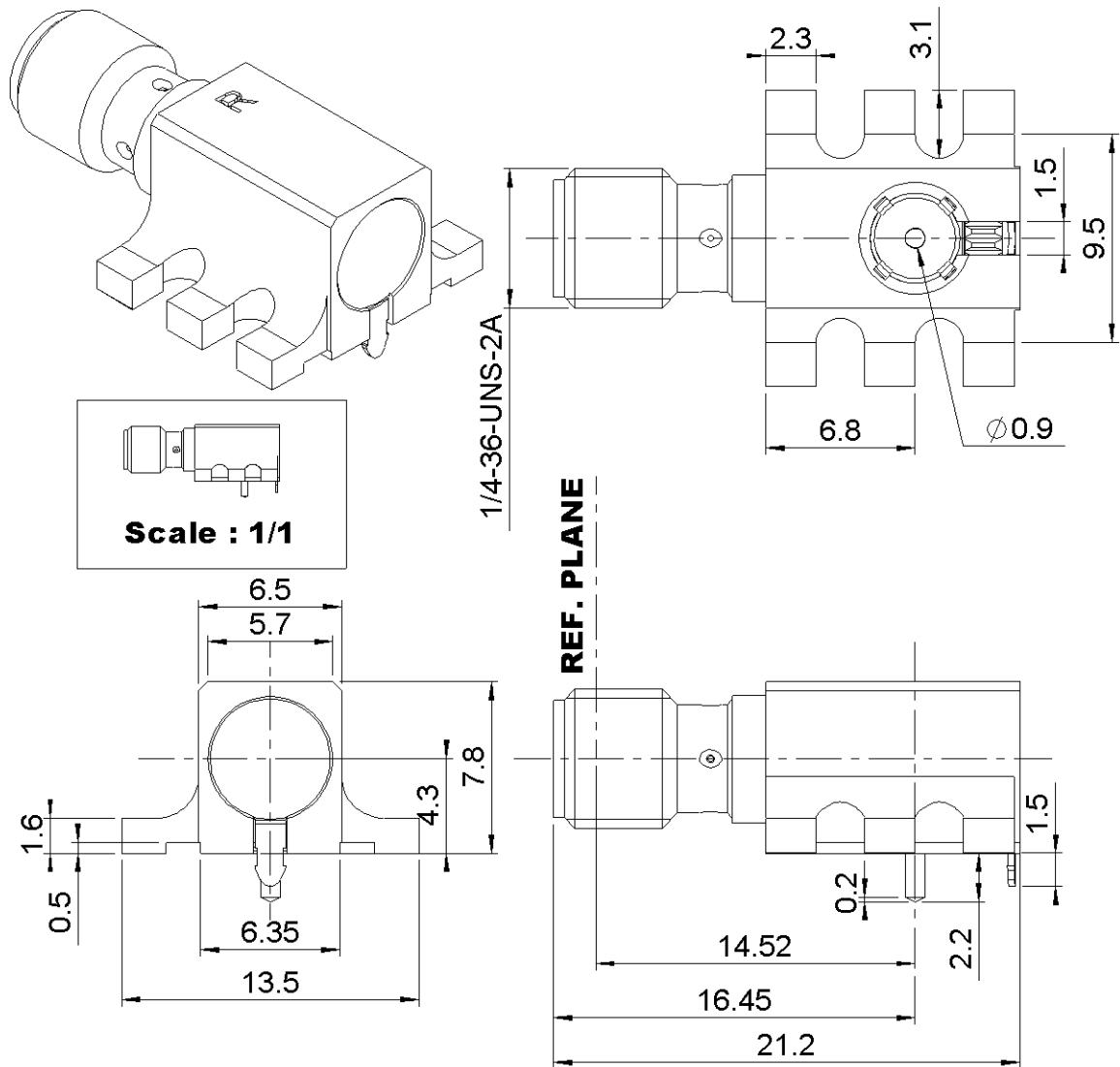
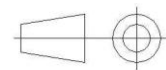


PAGE 1/5	ISSUE 1435D	SERIES SMA-COM	PART NUMBER R124682820
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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	BRASS	NPGR
Center contact	BERYLLIUM COPPER	GOLD OVER COPPER
Outer contact		
Insulator	PTFE	
Gasket		
Others parts	BRASS	GOLD OVER COPPER
-	-	-
-	-	-

PAGE 2/5	ISSUE 1435D	SERIES SMA-COM	PART NUMBER R124682820
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PACKAGING

Standard	Unit	Other
250	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-18	GHz
VSWR	* +	0.0000	x F(GHz) Maxi
Insertion loss		0.07	√F(GHz) dB Maxi
RF leakage	- (90	- F(GHz) dB Maxi
Voltage rating		350	Veff Maxi
Dielectric withstanding voltage		1000	Veff mini
Insulation resistance		5000	MΩ mini

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		27	N mini
Axial force – Opposite end		27	N mini
Torque		NA	N.cm mini
Recommended torque			
Mating		60	N.cm
Panel nut		NA	N.cm
Mating life		100	Cycles mini
Weight		5.7120	g

SPECIFICATION

1301-RNT 403 054 / 003 Rev. D

OTHER CHARACTERISTICS

Assembly instruction:

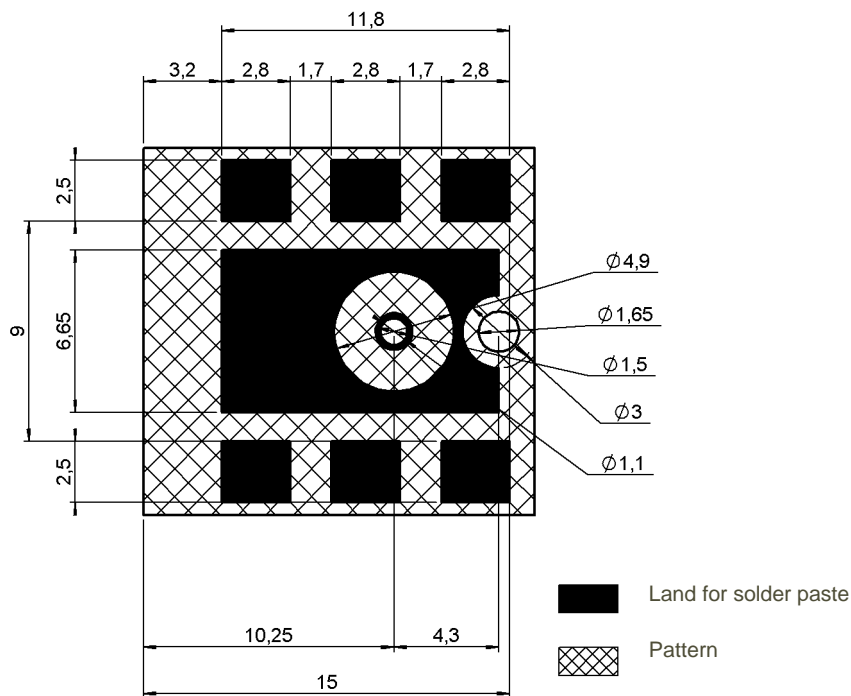
Others:

***Coaxial transmission line only
1.15 to 2GHz**

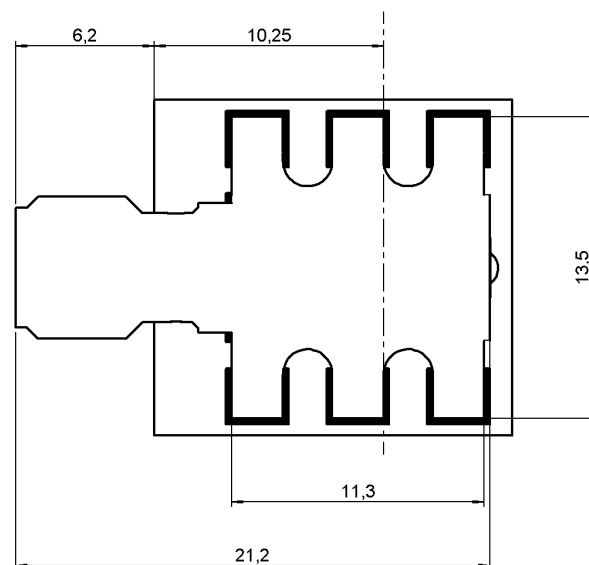
PAGE 3/5	ISSUE 1435D	SERIES SMA-COM	PART NUMBER R124682820
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SMA SERIES - INFORMATION

Coplanar line : pattern and signal are on the same side . Thickness of PCB : .063(1.6mm)
 The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed except for the land pattern on the PCB .



SHADOW OF SMA RECEPTACLE FOR VIDEO CAMERA

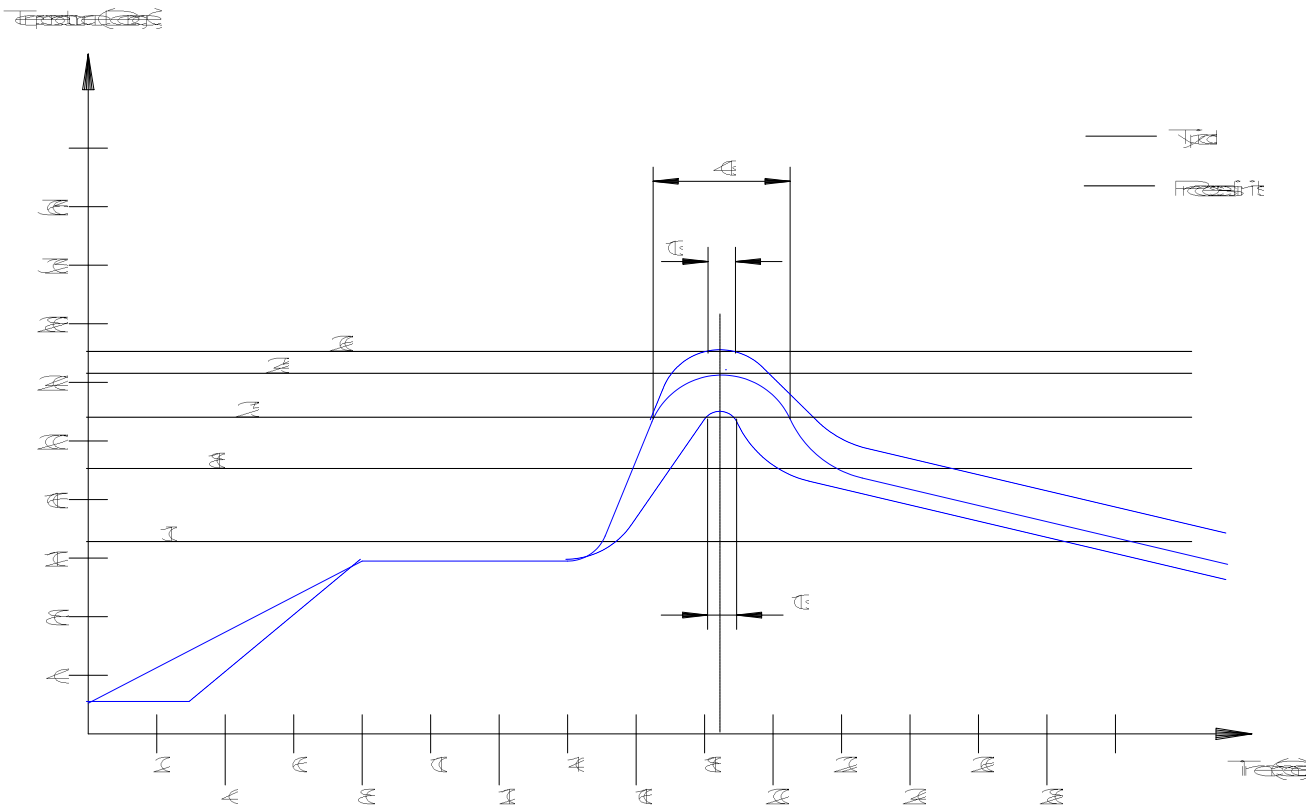


PAGE 4/5	ISSUE 1435D	SERIES SMA-COM	PART NUMBER R124682820
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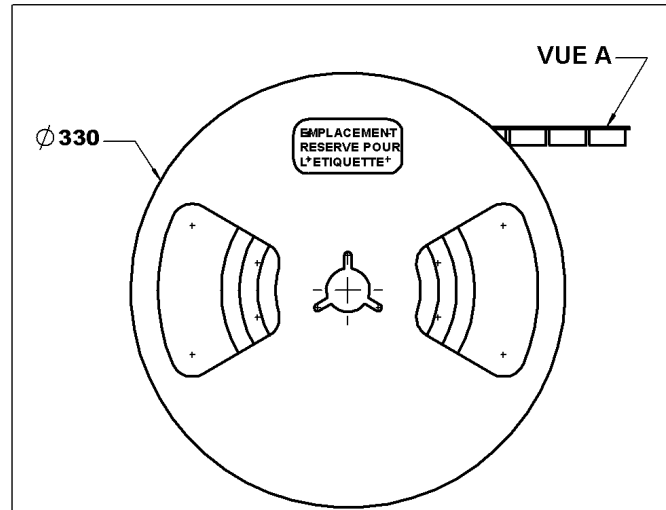
SOLDER PROCEDURE

1. Deposit solder paste 'SN62RP11AGS90' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm(5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is preferred to check the positioning of the component. Adhesive agents are forbidden on the receptacle.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

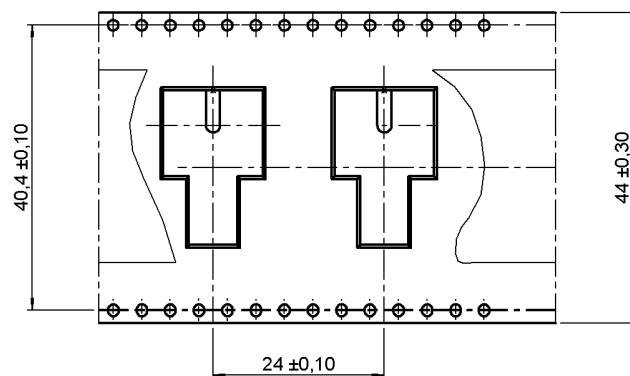
TEMPERATURE PROFIL



PAGE 5/5	ISSUE 1435D	SERIES SMA-COM	PART NUMBER R124682820
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bobine Ech :0.7



**Vue A (ech : 1.5)
sans connecteurs**